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REPORT DOCUMENTATION PAGE (SF298) (Continuation Sheet)

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Short Statement of Program Goals

The supported research sought to apply interference lithography technology as a tool for metrology in the sub-100 nm (nanometer) critical dimension (CD) linewidth regime. Semiconductor industry roadmaps show CDs shrinking to under 35 nm within 15 years. This requires mask image placement metrology accuracy of 9 2 nm by 2014. There are currently no industry length-scale calibration standards at any level of accuracy that may be used to ensure metrology tool accuracy. Instead, the industry relies on various self-referencing schemes which are inaccurate, expensive, time consuming, and ineffective. MIT developed technology to produce image placement metrology standards that achieved under 5 nm accuracy by the end of this Grant. Many other industrial and military electronics applications would issue from such super-accurate gratings, including encoders and integrated optoelectronic devices.

Accomplishments

MIT has completed the construction and testing of a novel lithography tool called the Nanoruler, which is capable of writing and reading large gratings with unprecedented accuracy. MIT have demonstrated the writing and reading of gratings with a phase stability and repeatability of well under 3 nm, 3

The Nanoruler utilizes the principle of scanning-beam interference lithography (SBIL), which involves the interference of small beams to create a grating "image," and then scanning a substrate under the image using a high-performance air-bearing stage. Stage and fringe phase errors are measured using heterodyne digital phase meters and locked out by use of acousto-optic phase shifters driven by a digital frequency synthesizer and high-speed digital controls. The Nanoruler is housed in a special environmental chamber to ensure the extremely tight environmental stability required to achieve nanometer fringe stability. Typical system positional stability during a period of 1 min has been demonstrated to be 2.1 nm, 3 . The Nanoruler is capable of patterning gratings and grids with periods down to 200 nm on 300 mm-diameter substrates.

One of the goals of the Nanoruler was to demonstrate that large, nano-accuracy gratings can be used as optical encoders to replace interferometers in lithography and metrology stages, thereby wringing out a large source of CD and overlay errors. Stage error is an important component of overlay and CD budgets. In reading

mode, the Nanoruler is designed to read the position and map the phase of gratings written by itself or other tools. In this mode, it thus performs essentially as an optical encoder with a precision of ~ 2 nm.

Improving stage error is becoming increasingly important as linewidths continue to shrink. A 2 nm stage position error is called for at the 30 nm node. Improved overlay and CD control are critically important for planar multilevel processing as the industry follows the high-volume manufacturing roadmap. However, it is of equal, if not greater importance for the low volume, high performance products of interest in defense electronics. Essentially handcrafted fixes to overlay and CD problems are becoming increasingly common as linewidths and k-factors shrink. These errors are increasingly driven by tool, pattern and process-dependant issues. While these costs can perhaps be bourn during high-volume production of consumer chips, during low-volume production by direct-write lithography of high-performance nanometer-sized devices, problems with CD and overlay control become increasingly expensive and time consuming to rectify.

Manuscripts submitted, but not yet published.

R121. "Effects of varying incident angle on the contrast of the fringe metrology using a Fresnel zone plate,"
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Student Master's Thesis

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Student Ph.D. Thesis

- Dr. Paul Thomas Konkola, *Design and Analysis of a Scanning Beam Interference Lithography System for Patterning Gratings with Nanometer-Level Distortion*, Ph.D. Thesis, Department of Mechanical Engineering, April 2003.
- Dr. Carl Gang Chen, Beam Alignment and Image Metrology for Scanning Beam Interference Lithography Fabricating Gratings with Nanometer Phase Accuracy, Ph.D. Thesis, Department of Electrical Engineering and Computer Science, April 2003.

Patents

"A method for interference lithography utilizing phase-locked scanning beams," M. L. Schattenburg and P. N. Everett, U. S. Patent (*pending*).

"Improved method for interferometric displacement measurement," R. K. Heilmann and M. L. Schattenburg, U. S. Patent (*pending*).

Technology Transfer

We have had the significant technical contacts with the following companies, including factory visits, phone calls, and meetings. These contacts specifically concerned MIT's technology in metrology, funded by this ARO contract.

Intel IBM Ultratech Corp. SVG Lithography Applied Materials (Etec) Motorola Texas Instruments